RELIABILITY REPORT

FOR

MAX3233ECWP+ / MAX3233EEWP+

PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED

160 Rio Robles

San Jose, CA 95134

 Eric Wright Reliability Engineer	 Brian Standley Manager, Reliability

Conclusion

The MAX3233ECWP+ / MAX3233EEWP+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX3233E/MAX3235E are EIA/TIA-232 and V.28/V.24 communications interfaces with automatic shutdown/wake-up features, high data-rate capabilities, and enhanced electrostatic discharge (ESD) protection. All transmitter outputs and receiver inputs are protected to ±15kV using IEC 1000-4-2 Air-Gap Discharge, to ±8kV using IEC 1000-4-2 Contact Discharge, and to ±15kV using the Human Body Model. The MAX3233E operates from a +3.3V supply; the MAX3235E operates from +5.0V.

All devices achieve a 1µA supply current using Maxim's revolutionary AutoShutdown Plus™ feature. These devices automatically enter a low-power shutdown mode when the following two conditions occur: either the RS-232 cable is disconnected or the transmitters of the connected peripherals are inactive, and the UART driving the transmitter inputs is inactive for more than 30 seconds. They turn on again when they sense a valid transition at any transmitter or receiver input. AutoShutdown Plus saves power without changes to the existing BIOS or operating system.

The MAX3233E/MAX3235E have internal dual charge pumps requiring no external capacitors. Both transceivers have a proprietary low-dropout transmitter output stage that enables true RS-232 performance from a +3.0V to +3.6V supply for the MAX3233E or a +4.5V to +5.5V supply for the MAX3235E. These devices are guaranteed to operate up to 250kbps. Both are available in space-saving 20-pin wide SO or plastic DIP packages.

II. Manufacturing Information

A. Description/Function:	±15kV ESD-Protected, 1µA, 250kbps, 3.3V/5V, Dual RS-232 Transceivers with Internal Capacitors
B. Process:	B3
C. Fabrication Location:	USA
D. Assembly Location:	Malaysia
E. Date of Initial Production:	4/24/1999

III. Packaging Information

A. Package Type:	20-pin SOIC (W)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non Conductive Epoxy
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#31-4847
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	100°C/W
K. Single Layer Theta Jc:	20°C/W
L. Multi Layer Theta Ja:	65.8°C/W
M. Multi Layer Theta Jc:	20°C/W

IV. Die Information

A. Dimensions:	91 X 159 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 476 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 2.26 \times 10^{-9}$

λ = 2.26 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the B3 Process results in a FIT Rate of 0.51 @ 25C and 8.79 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RS97/RS60 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX3233ECWP+ / MAX3233EEWP+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	476	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data